



## Material Content Data Sheet



<b>Sales Product Name</b>		ICB2FL02G		<b>Issued</b>		19. January 2018		
<b>MA#</b>		MA001123594						
<b>Package</b>		PG-DSO-19-5		<b>Weight*</b>		582.34 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.879	1.01	1.01	10096	10096
leadframe	inorganic material	phosphorus	7723-14-0	0.040	0.01		69	
	non noble metal	zinc	7440-66-6	0.160	0.03		275	
	non noble metal	iron	7439-89-6	3.200	0.55		5495	
wire	non noble metal	copper	7440-50-8	129.929	22.31	22.90	223117	228956
	noble metal	gold	7440-57-5	0.432	0.07	0.07	741	741
	encapsulation	organic material	carbon black	1333-86-4	1.309	0.22		2247
plastics	plastics	epoxy resin	-	42.312	7.27		72659	
	inorganic material	silicondioxide	60676-86-0	392.589	67.42	74.91	674159	749065
leadfinish	non noble metal	tin	7440-31-5	3.337	0.57	0.57	5730	5730
plating	noble metal	silver	7440-22-4	0.174	0.03	0.03	299	299
glue	plastics	acrylic resin	-	0.596	0.10		1023	
	noble metal	silver	7440-22-4	2.382	0.41	0.51	4090	5113
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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